

In the Specification:

On page 1, after the title insert the following:

**RELATED APPLICATIONS**

This is a U.S. national stage of application No. PCT/DE2004/002385, filed on 26 October 2004.

This patent application claims the priority of German patent application no. 103 61 650.0 filed December 30, 2003, the disclosure content of which is hereby incorporated by reference.

**FIELD OF THE INVENTION**

On page 1, amend the paragraph beginning on line 6 as follows:

The invention relates to an optoelectronic module with a carrier element, a semiconductor component on the carrier element, and an optical device assigned to the semiconductor component, ~~in accordance with the preamble of patent claim 1~~ and to a method for producing such an optoelectronic module ~~in accordance with the preamble of patent claim 10~~.

On page 1, delete the paragraph beginning on line 11 through line 13 in its entirety.

On page 1, before line 15, insert the following heading:

**BACKGROUND OF THE INVENTION**

On page 2, before line 7, insert the following heading:

## **SUMMARY OF THE INVENTION**

On page 2, amend the paragraph beginning on line 7 as follows:

One object of the present invention is to provide an optoelectronic module of the type mentioned above which has an improved optical connection between the semiconductor component and the optical device. ~~Furthermore, an intention is to specify~~

Another object is to provide a simple and cost-effective method for producing such an optoelectronic module.

On page 2, delete the paragraph beginning on line 15 through line 20 in its entirety.

On page 2, amend the paragraph beginning on line 22 as follows:

~~According to the invention, an optoelectronic module of the type mentioned at the beginning has a~~ These and other objects are attained in accordance with one aspect of the present invention directed to an optoelectronic module, comprising a carrier element having electrical connection electrodes and electrical lines, at least one semiconductor component for emitting or detecting electromagnetic radiation, said semiconductor component being applied on the carrier element and being electrically connected to connection electrodes of the carrier element and having a radiation coupling area, and at least one optical device assigned to the semiconductor component. A connecting layer made of a radiation-transmissive, deformable material is being arranged in a gap between the radiation coupling area and the optical device. The optical device

and the semiconductor component are fixed relative to one another in such a way that they are pressed against one another and that the connecting layer is thereby squeezed in such a way that it generates a force that strives to press the optical device and the radiation coupling area apart.

On page 5, amend the paragraph beginning on line 30 through page 6, line 5 as follows:

~~In a method of the type mentioned at the beginning, according to the invention, prior~~ One  
aspect of the invention is directed to a method for producing an optoelectronic module having at  
least the method steps of providing a carrier element having electrical connection electrodes and  
electrical lines, providing a semiconductor component for emitting or detecting electromagnetic  
radiation, said semiconductor component having a radiation coupling area, providing an optical  
device, applying the semiconductor component on the carrier element and electrically connecting  
the semiconductor component to the connection electrodes, and mounting the optical device  
above the radiation coupling area of the semiconductor component. Prior to mounting the  
optical device, a curable and – in the cured state – radiation-transmissive and deformable  
composition is applied at least over the radiation coupling area of the semiconductor component.  
Afterward, the applied composition is at least partly cured or let to be cured. In a further method  
step, the optical device and the semiconductor component are fixed relative to one another in  
such a way that they are pressed against one another and the composition is thereby squeezed in  
such a way that it generates a force that strives to press the optical device and the radiation  
coupling area apart.

On page 7, delete the paragraph beginning on line 1 through line 5 in its entirety.

On page 7, before line 7, insert the following heading:

**BRIEF DESCRIPTION OF THE DRAWINGS**

On page 7, before line 14, insert the following heading:

**DETAILED DESCRIPTION OF THE DRAWINGS**